

Customer No.: 31561
Application No.: 10/064,644
Docket No.: 9223-US-PA

REMARKS

I. Present Status of the Application

The Office Action objected the specification on grounds of non-descriptiveness of the title. The Office Action rejected claims 16-27 under 35 U.S.C. § 102(e) as being anticipated by Ohno (US Patent Application Publication 2002/0113319 A1, hereinafter "Ohno").

After entry of the above amendments, the title of the invention and claims 16 and 19 have been amended, and claims 16-27 are pending in the present application, with claims 16 and 19 being independent claims. Applicant believes that these changes do not introduce new matter and reconsideration of those claims is respectfully requested.

II. Response to Objections and Rejections

A. Objection to the specification

The Office Action, at page 2, objected the specification. The Examiner states that the title of the invention is not descriptive. In accordance with the Examiner's request, Applicants have changed the title of the invention. Accordingly, Applicant respectfully submits that the objection has been overcome and should be withdrawn.

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B. Rejections under 35 U.S.C. 102(e) over Ohno

The Office Action, at pages 3-4, rejected claims 16-27 under 35 U.S.C. § 102(e) as being anticipated by Ohno. Applicant respectfully traverses the rejection as applied to the amended claims for at least the reasons set forth below.

To anticipate a claim, the reference must teach each and every element of the claim. M.P.E.P. § 2131.

Independent claims 16 and 19 of the invention are respectively to provide a flip chip die, for joining with a flip-chip package substrate and the flip chip die, has *die pad rows outside the core die pads*, wherein the die pad rows “include signal die rows, *power die rows and ground die pad rows*.” Ohno, however, discloses a flip chip die having a plurality of outer portions of pads which have *only “signal pads”* but no power die rows or ground die pad rows (paragraphs [0041], lines 2-6; Items 31, 32 and 33 in Fig. 4). The “power supply pads” in Ohno’s disclosure are “in the intermediate area and the inner area on the pad forming layer,” and thus “[the] package substrate has the power supply pads inside of the signal pads” (paragraph [0040], lines 20-24; Items 11, 12, 13 and 14 in Fig. 3). In other words, Ohno discloses that the *power supply pads are actually belongs to the core die pads in the core area*, which is a feature rather different from what claimed in Applicant’s invention.

Moreover, the independent claim 19 is to provide a flip chip die, which comprises a group of “core die pads,” a plurality of “inner die pad rows,” and a plurality of “outer die pad

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rows." Ohno, however, fails to teach the outer die pad rows (Figs. 3, 4 and 6) as recited in claim 19.

Therefore, Ohno anticipates neither independent claim 16 nor independent claim 19 since Ohno does not disclose each and every element of the claims. Applicant notes that Examiner has also rejected claims 17-18 and 20-27 and Applicant respectfully disagrees with the Examiner's statements. Since claims 17-18 and 20-27 are dependent upon either claim 16 or claim 19 which are not anticipated by Ohno, claims 17-18 and 20-27 are consequently not anticipated by Ohno.

For at least the foregoing reasons, Applicant respectfully submits that the grounds of rejections have been addressed and the rejections overcome. Reconsideration and withdrawal of the rejections are respectfully requested.

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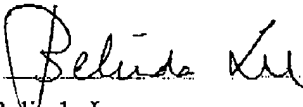
CONCLUSION

For at least the foregoing reasons, it is believed that the pending claims 16-27 are in proper condition for allowance. If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application, the Examiner is invited to call the undersigned.

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Respectfully submitted,


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